

Advanced Product Change Notification

202104052A: SOT505-2 Assembly Transfer from ATP to ATBK

Note: This notice is NXP Company

Proprietary.

Issue Date: May 06, 2021



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Management summary

SOT505-2 assembly will be discontinued at ATP and ATBK is add SOT505-2 assembly to maintain supply.

Change Category

[]Wafer Fab Process	[]Assembly Process	[X]Product Marking	[]Test Process	[]Design
[]Wafer Fab Materials	[X]Assembly Materials	[]Mechanical Specification	[]Test Equipment	[]Errata
[]Wafer Fab Location	[X]Assembly Location	[]Packing/Shipping/Labeling	[]Test Location	[]Electrical spec./Test coverage
[]Firmware	[]Other			
DCN Overview				

PCN Overview

Description

NXP is expanding ATBK assembly capabilities to include the part types in the attached file list. Mold compound and die adhesive materials in the ATBK manufacturing process will use the standard EMC-7470L-Q and QMI519 materials respectively. Additionally, ATBK will employ a roughened leadframe as a package quality improvement to reduce delamination. NXP has extensive manufacturing capabilities in the TSSOP8 family and with the critical demand for these products, these changes will help with timely deliveries.

Reason

Due to an increasing demand for SOT505-2 packaged devices and ATP discontinuance of supply over time, NXP is adding the ATBK flow as an alternate source to maintain timely deliveries.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples are available from Aug 02, 2021

Production

Shipment dates are product specific, see attached plan

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Self qualification: view online
Additional documents: view online
Timing and Logistics

The Self Qualification Report will be ready on Sep 01, 2021.

The Final PCN is planned to be issued on: Sep 01, 2021.

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Jun 05, 2021.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Steve Blozis

Position Marketing

e-mail

address <u>stephen.blozis@nxp.com</u>

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NXP Quality Management Team.

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